PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data	
1.1 Company	STMicroelectronics International N.V
1.2 PCI No.	MDG/17/10572
1.3 Title of PCI	New Tape Header finishing procedure for EEPROM in WLCSP
1.4 Product Category	EEPROM in WLCSP
1.5 Issue date	2017-11-21

2. PCI Team	
2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Benoit RODRIGUES
2.1.2 Marketing Manager	Hubert LEDUC
2.1.3 Quality Manager	Rita PAVANO

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Methods	Process flow chart: Revision change in Process/Recipe like addition, deletion of process step (process technology, sawing, die attach, plasma, marking, packing, labelling, transportation, etc..)	STATSChipPAC subcontractor

4. Description of change		
	Old	New
4.1 Description	- In the current situation, the header is linked to the protective belt. Then placing (at finishing step) or removing (at customer unreeling step) the protective belt could induce tension to the tape.	With the new procedure, the header is linked to itself and pasted to the protective belt (with the same ESD tape). Then, removing the protective belt will have less tension on the tape.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change	
5.1 Motivation	Reduction of potential tight winding of the tape.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change	
6.1 Description	N/A

7. Timing / schedule	
7.1 Date of qualification results	2017-11-21
7.2 Intended start of delivery	2017-12-11
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation			
8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)
10572 Public product.pdf 10572 PCI End of Tape WLCSP WITHOUT EPE- ALL CUSTOMERS -5-.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	M24C08-FCT6TP/T	
	M24C32-FCU6TP/TF	
	M24C64-FCU6TP/TF	
	M24C64M-FCU6T/TF	
	M24C64T-FCU6T/TF	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

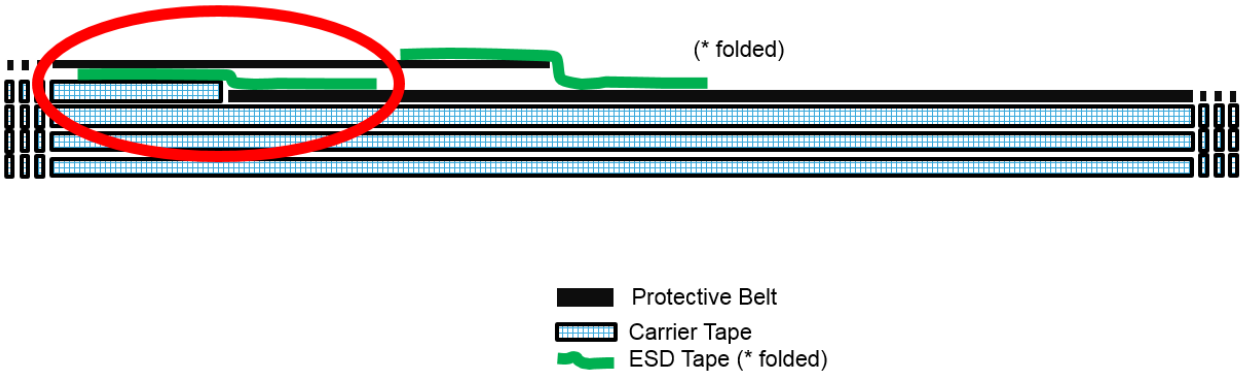
PRODUCT / PROCESS CHANGE INFORMATION

New Tape Header finishing procedure for EEPROM in WLCSP

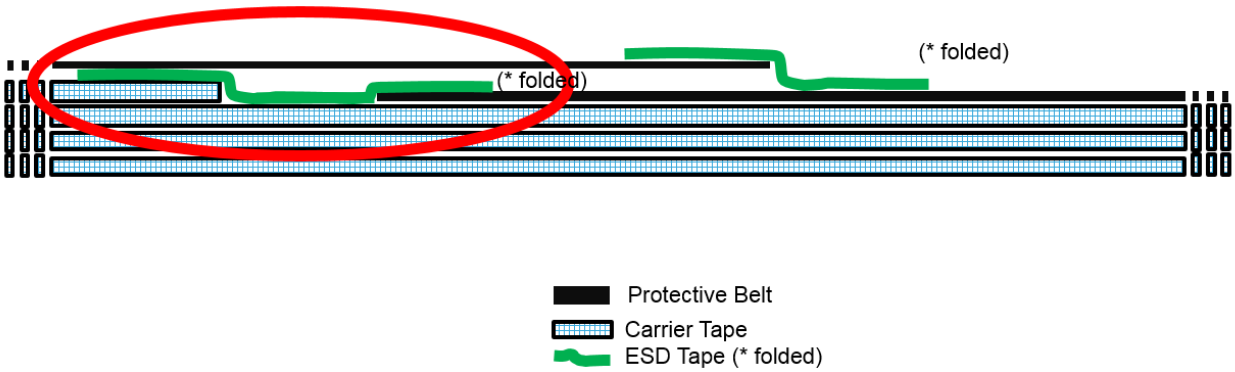
What is the change?

ST is modifying the Tape Header finishing procedure of its WLCSP assembled at STATSChipPAC (Singapore):

- In the **current situation**, the **header is linked to the protective belt**. Then placing (at finishing step) or removing (at customer unreeling step) the protective belt could induce tension to the tape.



- With the **new procedure**, the **header is linked to itself <u>and</u> pasted to the protective belt** (with the same ESD tape). Then, removing the protective belt will have less tension on the tape.



Why?

With the **new procedure**, placing or removing the protective belt will avoid potential tension to the tape at STATSChipPAC finishing or at unreeling step at customer.

When?

New procedure for tape header finishing for all EEPROM WLCSP products will start from beginning of December 2017.

How will the change be qualified?

The **qualification** of this **new procedure** has been performed using the standard ST Microelectronics Corporate Procedures for Quality & Reliability and the Best Known Method (BKM) defined for WLCSP finishing.

What is the impact of the change?

- **Form, Fit, Function:** No change

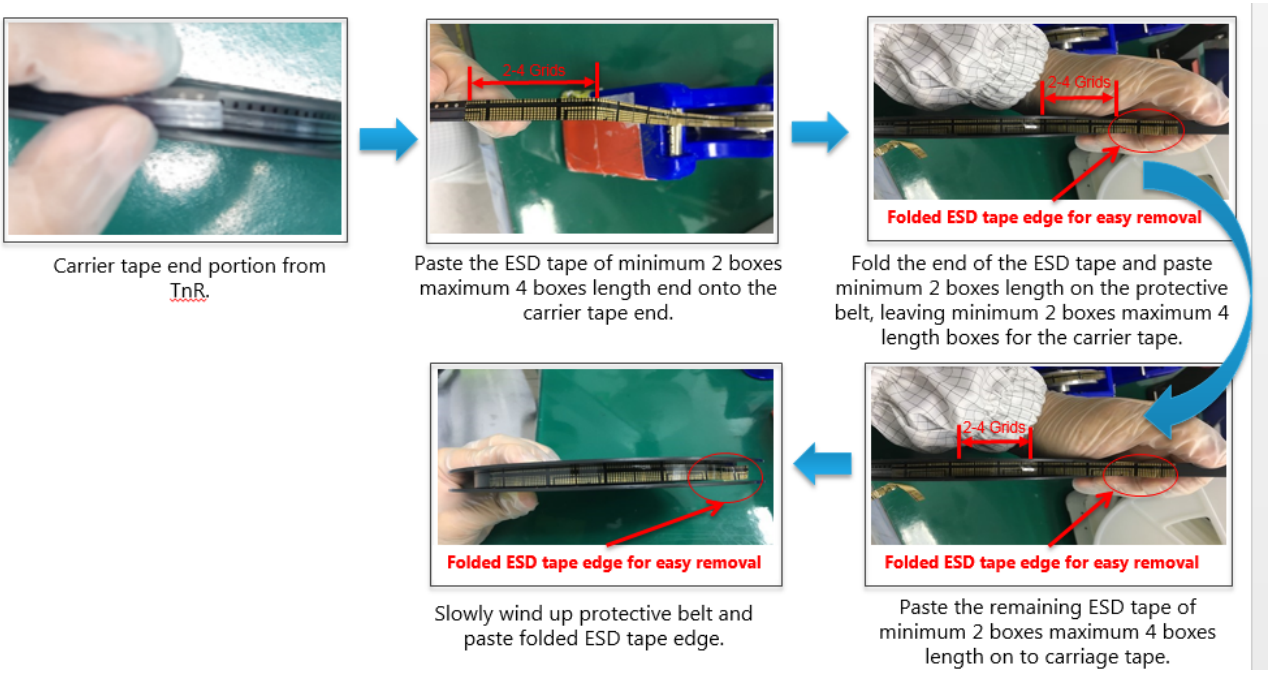
Appendix A: Product Change Information

Product family / Commercial products:	EEPROM WLCSP
Customer(s):	All
Type of change:	New procedure for End of Tape (header) finishing
Reason for the change:	Quality improvement
Description of the change:	New “End of Tape” procedure for EEPROM WLCSP finis hing at STATSChipPAC (Singapore)
Forecast date of the change: (Notification to customer)	Week 47 / 2017
Forecast date of Qualification samples availability for customer(s):	N/A
Product Line(s) and/or Part Number(s):	See APPENDIX B
Estimated date of first shipment:	Week 50 / 2017

Appendix B: Concerned Commercial Part Numbers:

M24C64T-FCU6T/TF
M24C64-FCU6TP/TF
M24C64M-FCU6T/TF
M24C32-FCU6TP/TF
M24C32-FCU6TP/T
M24C08-FCT6TP/T

CURRENT PROCEDURE FOR REELING



NEW PROCEDURE FOR REELING

Document Revision History		
Date	Rev.	Description of the Revision
Oct. 27, 2017	1.00	First draft creation – Christian POLI

Source Documents & Reference Documents		
Source document Title	**Rev.:**	**Date:**